


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/19/11892	
1.3 Title of PCN	VIPower Products (TO-220): New Mold Compound Introduction (Hysol GR30)	
1.4 Product Category	See list	
1.5 Issue date	2019-12-18	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANCKE CHRISTIANE
2.1.2 Phone	+49 89460062128
2.1.3 Email	christiane.francke@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Mario ASTUTI,Nicola LIPORACE
2.1.2 Marketing Manager	Stello Matteo BILLE'
2.1.3 Quality Manager	Francesco MINERVA

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	ST Shenzhen (China)

4. Description of change

	Old	New
4.1 Description	Molding compound Samsung SI-7200DXC	Molding compound Loctite Hysol GR30
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impct	

5. Reason / motivation for change

5.1 Motivation	Discontinuation of current Samsung Mold Compound. Following PCI CRP/19/11478
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes
-----------------	-------------------------------

7. Timing / schedule

7.1 Date of qualification results	2019-12-04
7.2 Intended start of delivery	2020-02-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11892 Validation.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-12-18

9. Attachments (additional documentations)

11892 Public product.pdf
11892 Validation.pdf
11892 Details.pdf

10. Affected parts

10. 1 Current			10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	VNP10N07-E		

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics – All rights reserved